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MC100LVEL59

3.3 V ECL Triple 2:1 Multiplexer

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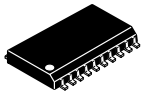


SOIC−20 WB
DW SUFFIX
CASE 751D

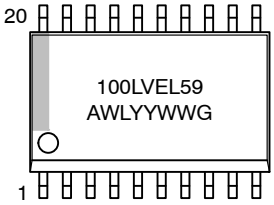
Description

The MC100LVEL59 is a 3.3 V triple 2:1 multiplexer with differential outputs. The output data of the multiplexers can be controlled individually via the select inputs or as a group via the common select input. The flexible selection scheme makes the device useful for both data path and random logic applications.

Features

- Individual or Common Select Controls
- 500 ps Typical Propagation Delays
- ESD Protection: > 2 kV HBM
- The 100 Series Contains Temperature Compensation
- PECL Mode Operating Range: V_{CC} = 3.0 V to 3.8 V with V_{EE} = 0 V
- NECL Mode Operating Range: V_{CC} = 0 V with V_{EE} = −3.0 V to −3.8 V
- Internal Input Pulldown Resistors
- Q Output will Default LOW with Inputs Open or at V_{EE}
- Meets or Exceeds JEDEC Spec EIA/JESD78 IC Latchup Test
- Moisture Sensitivity: Level 3 (Pb-free)
  For Additional Information, see Application Note AND8003/D
- Flammability Rating: UL 94 V−O @ 0.125 in, Oxygen Index 28 to 34
- Transistor Count = 182 devices
- These Devices are Pb-Free and are ROHS Compliant

MARKING DIAGRAM*

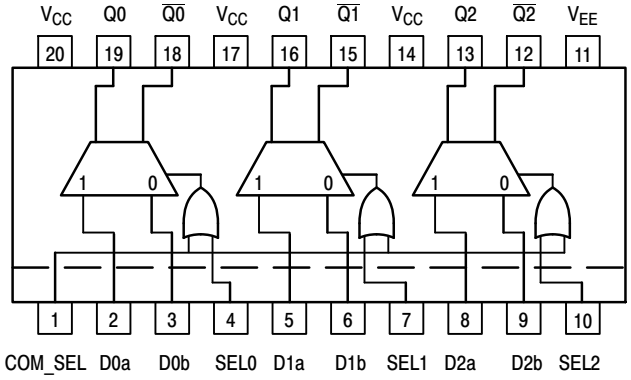


A	= Assembly Location
WL	= Wafer Lot
YY	= Year
WW	= Work Week
G	= Pb-Free Package

*For additional marking information, refer to Application Note AND8002/D.

ORDERING INFORMATION

Device	Package	Shipping
MC100LVEL59DWG	SOIC−20 WB (Pb-Free)	38 Units/Tube



Warning: All V_{CC} and V_{EE} pins must be externally connected to Power Supply to guarantee proper operation.

Figure 1. Logic Diagram and Pinout: 20—Lead SOIC (Top View)

Table 1. PIN DESCRIPTION

Pins	Function
D0a-D2a	ECL Input Data a
D0b-D2b	ECL Input Data b
SEL0-SEL2	ECL Individual Select Input
COM_SEL	ECL Common Select Input
Q0-Q2; $\overline{Q0}$-$\overline{Q2}$	ECL Differential Outputs
V_{CC}	Positive Supply
V_{EE}	Negative Supply

Table 2. TRUTH TABLE

SEL	Data
H	a
L	b

Table 3. MAXIMUM RATINGS

Symbol	Parameter	Condition 1	Condition 2	Rating	Unit
V_{CC}	PECL Mode Power Supply	V_{EE} = 0 V		8 to 0	V
V_{EE}	NECL Mode Power Supply	V_{CC} = 0 V		−8 to 0	V
V_I	PECL Mode Input Voltage NECL Mode Input Voltage	V_{EE} = 0 V V_{CC} = 0 V	$V_I \le V_{CC}$ $V_I \ge V_{EE}$	6 to 0 −6 to 0	V
I_{out}	Output Current	Continuous Surge		50 100	mA
T_A	Operating Temperature Range			−40 to +85	°C
T_{stg}	Storage Temperature Range			−65 to +150	°C
θ_{JA}	Thermal Resistance (Junction to Ambient)	0 lfpm 500 lfpm	SOIC−20 WB	140 100	°C/W
θ_{JC}	Thermal Resistance (Junction to Case)	Standard Board	SOIC−20 WB	30 to 35	°C/W
T_{sol}	Wave Solder	< 2 to 3 sec @ 248°C		265	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

Table 4. LVPECL DC CHARACTERISTICS (V_{CC}= 3.3 V; V_{EE}= 0.0 V (Note 1))

Symbol	Characteristic	–40°C			25°C			85°C			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
I_{EE}	Power Supply Current		27	32		27	32		27	32	mA
V_{OH}	Output HIGH Voltage (Note 2)	2215	2295	2420	2275	2345	2420	2275	2345	2420	mV
V_{OL}	Output LOW Voltage (Note 2)	1470	1605	1745	1490	1595	1680	1490	1595	1680	mV
V_{IH}	Input HIGH Voltage	2135		2420	2135		2420	2135		2420	mV
V_{IL}	Input LOW Voltage	1490		1825	1490		1825	1490		1825	mV
I_{IH}	Input HIGH Current			150			150			150	μA
I_{IL}	Input LOW Current	0.5			0.5			0.5			μA

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

1. Input and output parameters vary 1:1 with V_{CC}. V_{EE} can vary ±0.3 V.
2. Outputs are terminated through a 50 Ω resistor to V_{CC} – 2.0 V.

Table 5. LVNECL DC CHARACTERISTICS (V_{CC}= 0.0 V; V_{EE}= –3.3 V (Note 1))

Symbol	Characteristic	–40°C			25°C			85°C			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
I_{EE}	Power Supply Current		27	32		27	32		27	32	mA
V_{OH}	Output HIGH Voltage (Note 2)	–1085	–1005	–880	–1025	–955	–880	–1025	–955	–880	mV
V_{OL}	Output LOW Voltage (Note 2)	–1830	–1695	–1555	–1810	–1705	–1620	–1810	–1705	–1620	mV
V_{IH}	Input HIGH Voltage	–1165		–880	–1165		–880	–1165		–880	mV
V_{IL}	Input LOW Voltage	–1810		–1475	–1810		–1475	–1810		–1475	mV
I_{IH}	Input HIGH Current			150			150			150	μA
I_{IL}	Input LOW Current	0.5			0.5			0.5			μA

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

1. Input and output parameters vary 1:1 with V_{CC}. V_{EE} can vary ±0.3 V.
2. Outputs are terminated through a 50 Ω resistor to V_{CC} – 2.0 V.

Table 6. AC CHARACTERISTICS (V_{CC}= 3.3 V; V_{EE}= 0.0 V or V_{CC}= 0.0 V; V_{EE}= −3.3 V (Note 3))

Symbol	Characteristic	−40°C			25°C			85°C			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
fmax	Maximum Toggle Frequency		TBD			TBD			TBD		GHz
t_{PLH} t_{PHL}	Propagation DATA to Q/$\overline{Q}$ Delay SEL to Q/$\overline{Q}$ COM_SEL to Q/$\overline{Q}$	 340 340 340		 690 690 690	 340 340 340		 690 690 690	 340 340 340		 690 690 690	ps
t_{skew}	Output-Output Skew Any D_n, D_m to Q			 100			 100			 100	ps
tJITTER	Cycle-to-Cycle Jitter		TBD			TBD			TBD		ps
t_r t_f	Output Rise/Fall Times Q (20% − 80%)	200		540	200		540	200		540	ps

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

3. V_{EE} can vary ±0.3 V.

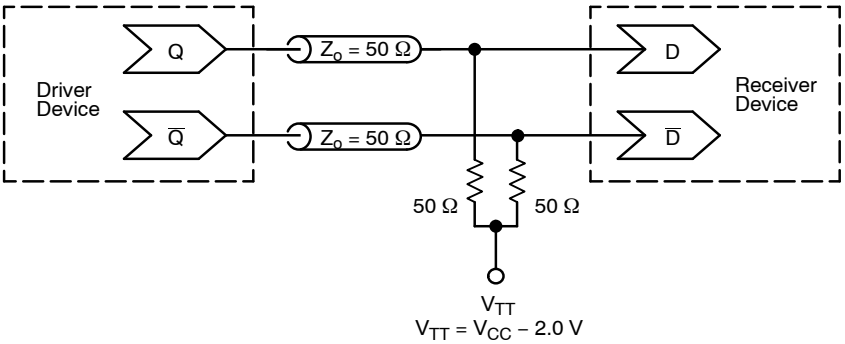


Figure 2. Typical Termination for Output Driver and Device Evaluation (See Application Note AND8020/D – Termination of ECL Logic Devices.)

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

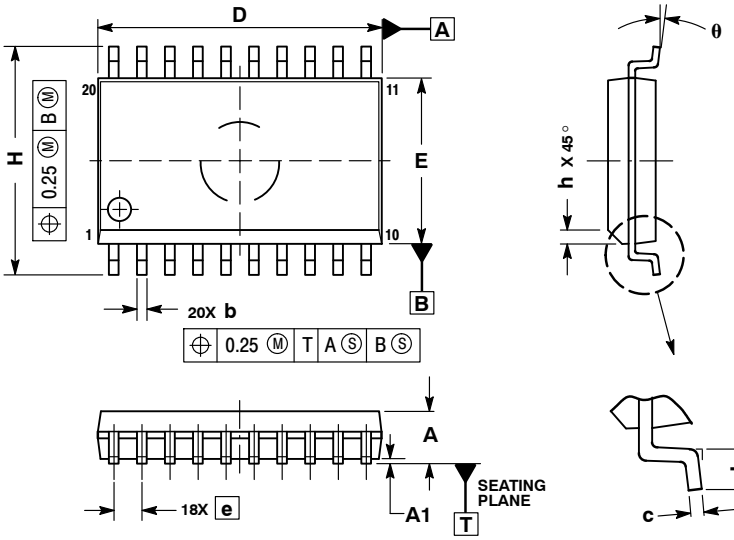
Resource Reference of Application Notes

AN1405/D – ECL Clock Distribution Techniques
AN1406/D – Designing with PECL (ECL at +5.0 V)
AN1503/D – ECLinPS I/O SPiCE Modeling Kit
AN1504/D – Metastability and the ECLinPS Family
AN1568/D – Interfacing Between LVDS and ECL
AN1672/D – The ECL Translator Guide
AND8001/D – Odd Number Counters Design
AND8002/D – Marking and Date Codes
AND8020/D – Termination of ECL Logic Devices
AND8066/D – Interfacing with ECLinPS
AND8090/D – AC Characteristics of ECL Devices

MC100LVEL59

PACKAGE DIMENSIONS

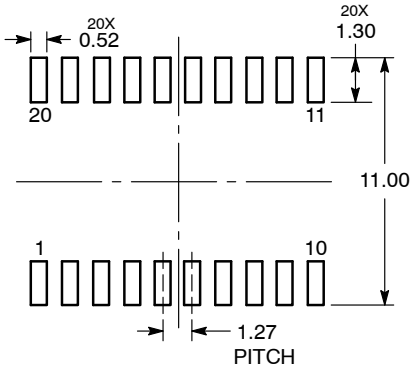
SOIC−20 WB
CASE 751D−05
ISSUE H



NOTES:
1. DIMENSIONS ARE IN MILLIMETERS.
2. INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 1994.
3. DIMENSIONS D AND E DO NOT INCLUDE MOLD PROTRUSION.
4. MAXIMUM MOLD PROTRUSION 0.15 PER SIDE.
5. DIMENSION B DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE PROTRUSION SHALL BE 0.13 TOTAL IN EXCESS OF B DIMENSION AT MAXIMUM MATERIAL CONDITION.

	MILLIMETERS	
DIM	MIN	MAX
A	2.35	2.65
A1	0.10	0.25
b	0.35	0.49
c	0.23	0.32
D	12.65	12.95
E	7.40	7.60
e	1.27 BSC	
H	10.05	10.55
h	0.25	0.75
L	0.50	0.90
θ	0°	7°

RECOMMENDED SOLDERING FOOTPRINT*



DIMENSIONS: MILLIMETERS

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/Ds.

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